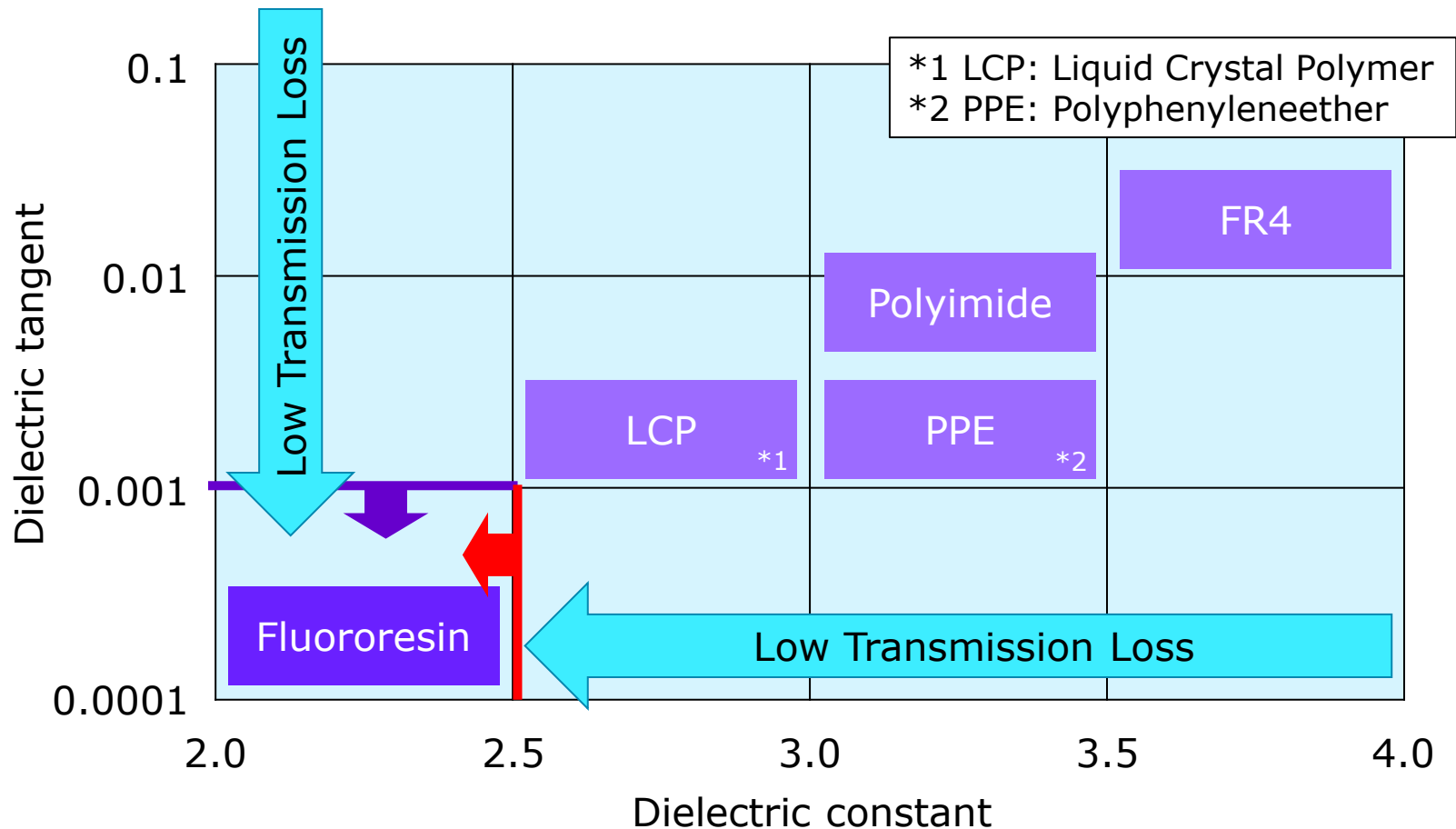


Spec comparison of each FPC base material



Fluoropolymers have the lowest dielectric constant and dielectric tangent among resins, and are characterized by their ability to minimize transmission loss in the transmission of high-frequency signals. Although there are materials with low dielectric constant such as polypropylene, they cannot be used for circuit boards because their heat resistance is about 150 degC and they cannot be soldered. Fluoropolymers have a heat resistance of 280degC or higher, making them suitable for use in circuit boards. The ability to achieve both of low transmission loss and heat resistance is a unique property derived from the molecular structure of fluoropolymers, and is impossible to achieve with any other polymers.